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THERMAL MONITORING SYSTEM FOR SEMICONDUCTOR DEVICES

ABSTRACT

A method for monitoring the operating temperature of a semiconductor device (309). The method comprising the steps of: placing a thermal coupling material (307) between the bottom of the semiconductor device (309) and the top of a printed circuit board (301) for inserting the device (309) thereinto; inserting a sensor (303) so to be at least partially covered by the thermal coupling material (307); and measuring the temperature from the sensor (303) within a predetermined time interval. In accordance with another aspect of the invention, an apparatus is described to carry out the above process.

FIG 3

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